FAIRCI SEMICOND FDC6302P	DUCTOR				October 1997
•	Γ, Dual P-Chanr	nel	Features		
General Description These Dual P-Channel logic level enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors in load switchimg applications. Since bias resistors are not required this one P-Channel FET can replace several digital transistors with different bias resistors like the IMBxA series.		 -25 V, -0.12 A continuous, -0.5 A Peak. R_{DS(ON)} = 13 Ω @ V_{GS}= -2.7 V R_{DS(ON)} = 10 Ω @ V_{GS}= -4.5 V. Very low level gate drive requirements allowing direct operation in 3V circuits. V_{GS(th)} < 1.5V. Gate-Source Zener for ESD ruggedness. >6kV Human Body Model Replace multiple PNP digital transistors (IMHxA series) wi one DMOS FET. 			
, A					
SOT-23	SuperSOT [™] -6	SuperSOT [™] -8	SO-8	SOT-223	SOIC-16
	D1 D1 SOT ™-6 ^{pin1} G1	G2 S2			3

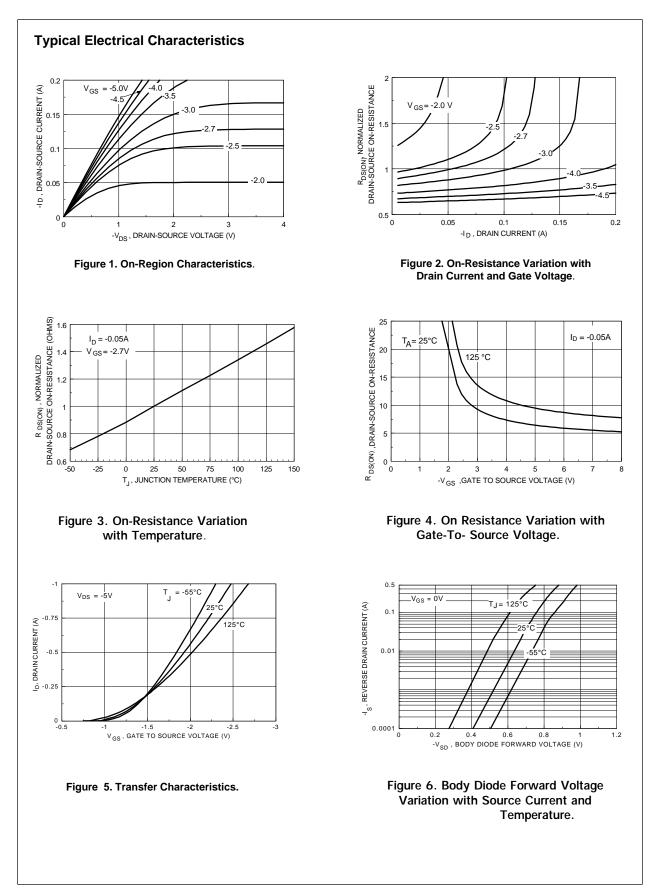
Absolute Maximum Ratings $T_{A} = 25^{\circ}C$ unless other wise noted

Symbol	Parameter		FDC6302P	Units
V _{DSS}	Drain-Source Voltage		-25	V
V _{GSS}	Gate-Source Voltage		-8	V
D	Drain Current - Continuous - Pulsed		-0.12	A
			-0.5	
P _D	Maximum Power Dissipation	(Note 1a)	0.9	W
		(Note 1b)	0.7	
T_,T _{stg}	Operating and Storage Temperature R	ange	-55 to 150	C°
ESD	Electrostatic Discharge Rating MIL-ST Human Body Model (100pf / 1500 Ohr		6.0	kV
THERMA	L CHARACTERISTICS			
R _{eja}	Thermal Resistance, Junction-to-Ambie	ent (Note 1a)	140	°C/W
R _{euc}	Thermal Resistance, Junction-to-Case	(Note 1)	60	°C/W

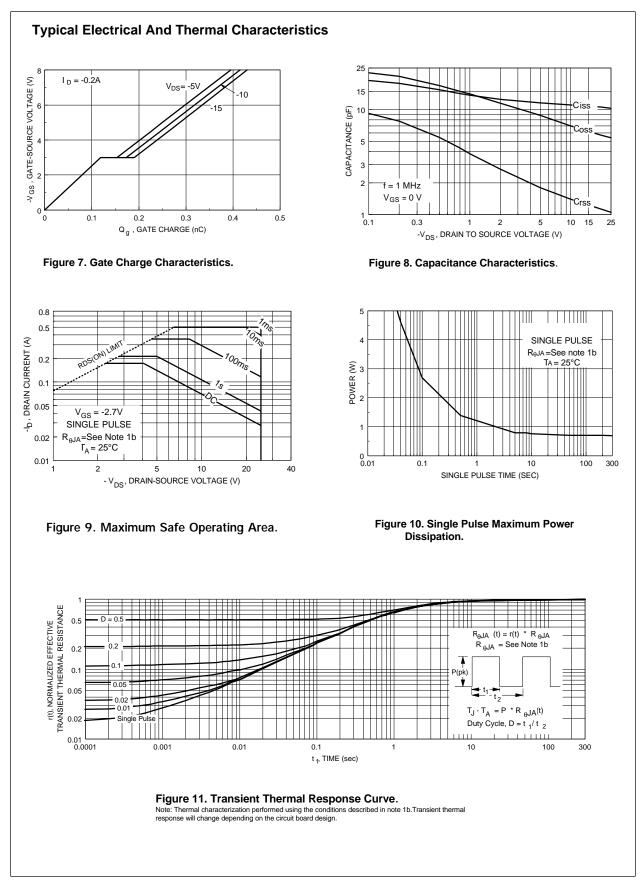
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Symbol	Parameter	Conditions	Min	Тур	Max	Units
OFF CHAR	ACTERISTICS					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_{D} = -250 \mu A$	-25			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_{\rm D}$ = -250 µA, Referenced to 25 °C		-20		mV /°C
DSS	Zero Gate Voltage Drain Current	$V_{DS} = -20 V, V_{GS} = 0 V$			-1	μA
		$T_{J} = 55^{\circ}C$			-10	μA
GSS	Gate - Body Leakage Current	$V_{GS} = -8 V, V_{DS} = 0 V$			-100	nA
	CTERISTICS (Note 2)					
$\Delta V_{GS(th)} / \Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	I_{D} = -250 µA, Referenced to 25 °C		1.9		mV /°C
V _{GS(th)}	Gate Threshold Voltage	$V_{\rm DS} = V_{\rm GS}, \ I_{\rm D} = -250 \ \mu {\rm A}$	-0.65	-1	-1.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = -2.7 \text{ V}, I_{D} = -0.05 \text{ A}$		10.6	13	Ω
		$V_{GS} = -4.5 \text{ V}, I_{D} = -0.2 \text{ A}$		7.9	10	1
		T _J =125°C		12	18	
D(ON)	On-State Drain Current	$V_{GS} = -2.7 \text{ V}, V_{DS} = -5 \text{ V}$	-0.05			А
9 _{FS}	Forward Transconductance	$V_{\rm DS} = -5 \text{ V}, \ \text{I}_{\rm D} = -0.2 \text{ A}$		0.135		S
DYNAMIC C	CHARACTERISTICS	·				
C _{iss}	Input Capacitance	$V_{DS} = -10 V, V_{GS} = 0 V,$ f = 1.0 MHz		11		pF
C _{oss}	Output Capacitance	t = 1.0 MHz		7		pF
C _{rss}	Reverse Transfer Capacitance			1.4		pF
SWITCHING	CHARACTERISTICS (Note 2)					
t _{D(on)}	Turn - On Delay Time	$V_{DD} = -6 V, I_{D} = -0.2 A,$		5	12	ns
ţ,	Turn - On Rise Time	$V_{\rm GS}$ = -4.5 V, R _{GEN} = 50 Ω		8	16	ns
D(off)	Turn - Off Delay Time			9	18	ns
t _f	Turn - Off Fall Time			5	10	ns
Q _g	Total Gate Charge	$V_{\rm DS} = -5 \text{ V}, \text{ I}_{\rm D} = -0.2 \text{ A},$		0.22	0.31	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -4.5 V		0.12		nC
Q _{gd}	Gate-Drain Charge			0.05		nC
DRAIN-SOU	IRCE DIODE CHARACTERISTICS AND MAXI	IMUM RATINGS	1			1
s	Maximum Continuous Drain-Source Diode For				-0.7	A
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = -0.7 A$ (Note 2)		-1	-1.3	V
design while F	m of the junction-to-case and case-to-ambient thermal resistance where R_{BcA} is determined by the user's board design. 140°C/W on a 0.125 in ² pad of 202 copper. Use Width ≤ 300µs, Duty Cycle ≤ 2.0%.	W on a 0.005 in ² of pad			gut i Gra	

FDC6302P Rev.C



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